



PRESS RELEASE

FOR IMMEDIATE RELEASE

High-Speed Bondtesting Guidebook available from Dage

June 26, 2007, Fremont, California – Dage Precision Industries, the industry leader in digital x-ray inspection and bondtesting technology, is pleased to announce that a reference booklet entitled “High-Speed Bondtesting – Understanding the Technology” is available to the electronics assembly industry.

The Dage high-speed bondtesting guidebook provides valuable information that can be used as a teaching aid and reference guide for anyone undertaking reliability testing of BGA and CSP solder ball interconnections. The contents of the guidebook includes information on the theory and practice of high-speed bondtesting, impact testing applications, evaluation of pad finishes and solder ball alloys, as well as lead-free solder ball joint evaluation and brittle fracture joint failure analysis.

“JEDEC has recently published a new standard for high-speed shear and cold bump pull bondtesting,” stated Stephen Clark, bondtester product manager for Dage Precision Industries. “This guidebook contains ideal training material for those new to the technique of high-speed bondtesting, as well as those who what to fully understand what is required to be in full compliance with these new JEDEC standards and to ensure comprehensive analysis of microelectronic solder joint integrity and reliability.”

Presented in 30 pages and illustrated with numerous images and diagrams, the high-speed bondtesting guidebook can be obtained by contacting your local Dage sales office or sales@dage-group.com and will be delivered by a Dage sales representative.

With America's headquarters located in Fremont, California, Dage Precision Industries, Inc. manufactures and supports a complete range of award winning digital x-ray inspection systems and bond test equipment for the printed circuit board assembly and semiconductor industries. For more information, visit www.dage-group.com.

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